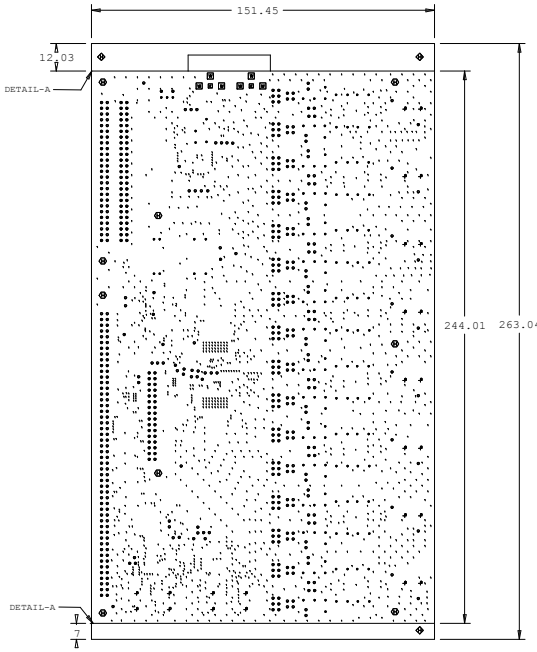
REVISIONS		
REV #	DESCRIPTION	DATE
REV #	CCN #	DDMMYY

FABRICATION NOTES:

1. EPOXY FIBERGLASS FR4 GRADE HIGH Tg LAMINATE STRUCTURE FOR CORE AND COPPER THICKNESS TYPE GFR, GRADE4,CLASS1, CLASS4.
2. UNLESS OTHERWISE SPECIFIED ALL THE HOLE DIMENSIONS APPLY AFTER PLATING.
3. ALL PLATED THROU HOLES TO HAVE A MINIMUM OF 0.001" COPPER.
4. ALL HOLES SHALL LOCATE WITHIN +/-0.003" DIAMETER OF THE TRUE POSITION.
5. ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANNULAR RING OF 0.003".
6. ELECTROLESS NICKEL/GOLD(NI/AU) FINISH NI - MICRONS AU- MICRONS.
7. APPLY SOLDERMASK OVER BARE COPPER. SOLDER MASK TO BE PER IPC-SM840. TYPE-A, CLASS 2, COLOR: TRANSPARENT GREEN.
8. SILKSCREEN USING WHITE EPOXY PERMANENT, ORGANIC, NON CONDUCTIVE INK.
9. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PAD.
10. NET TEST REQUIRED FOR SHORTS AND OPENS.
11. AUTOMATED OPTICAL INSPECTION OF ALL LAYERS IS REQUIRED.
12. WARP OR TWIST OF BOARD SHALL NOT EXCEED .010" PER INCH.
13. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- .001" OF ARTWORK ORIGINALS.
14. BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATION OF 94V-0.VENDORS UL LOGO SHALL BE PERMANENTLY INSERTED ON THE BOARD.
15. FABRICATION IN ACCORDANCE WITH IPC-4012, CLASS2, PER IPC-4011.
16. BOARD SHALL BE FREE FROM FIBREGLASS DUST OR ANY OTHER FOREIGN MATERIAL.
17. PCB MUST BE FABRICATED AS PER LAYER STACKUP PROVIDED.
18. THIEVING IS ALLOWED ONLY ON PCB FRAME(NOTE IN CIRCUIT AREA).
19. MINIMUM TRACE WIDTH AND SPACING : .006" / .006".
20. TEARDROPS MAY BE ADDED TO VIA PADS OR SIGNAL LAYERS TO IMPROVE YIELDS. MAINTAINING CURRENT LINE WIDTH AND SPACING.
21. FINISHED BOARD THICKNESS .045" +/- 10%.
22. ALL VIAS SHOULD BE TENTED UNLESS OTHERWISE SPECIFIED.



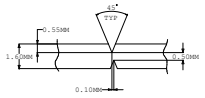
DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
·	8.0	PLATED	1794
•	30.0	PLATED	138
•	34.0	PLATED	5
•	40.0	PLATED	183
•	42.0	PLATED	100
•	44.0	PLATED	66
•	46.0	PLATED	98
•	46.0	PLATED	32
•	48.0	PLATED	50
⊠	68.0	PLATED	2
▣	104.0	PLATED	6
⊛	126.0	PLATED	9
*	66.0	NON-PLATED	24
✥	126.0	NON-PLATED	3

IMPEDANCE SPECIFICATIONS

SL#	TYPE	LAYER	TRACEWIDTH(Mils)	SPACING(Mils)	IMPEDANCE(Ohms)	REF LAYER
01	MICROSTRIP	L1/L4	6	NA	50	L2/L3

LAYER STACKUP

LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS [INCHES]
PRIMARY SIDE SILKSCREEN			
PRIMARY SIDE SOLDERMASK			
L01 PRIMARY SIDE	1.5oz.		0.0037
L02 GROUND-PLANE	1oz.		0.047
L03 POWER-PLANE	1oz.		0.0037
L04 SECONDARY SIDE	1.5oz.		
SECONDARY SIDE SOLDERMASK			
SECONDARY SIDE SILKSCREEN			



DETAIL-A(V-GROOVE DETAILS)
SCALE:NTS

MISTRAL SOLUTIONS PVT LTD.
#60, ADARSH REGENT, 100' FEET RING ROAD,
DOMLUR EXTENSION, BANGALORE 560 071.

PCB,
GALILEO AUDIO DAUGHTER CARD

	APPROVALS	DATE	SIZE	DRAWING NO.	REV
DRAWN	RA	240915	D	FY150306000202	B
CHECKED	ZA	240915			
APPROVED	VB	240915	SCALE:NONE	FILE NAME:	SHEET 1 OF 11